

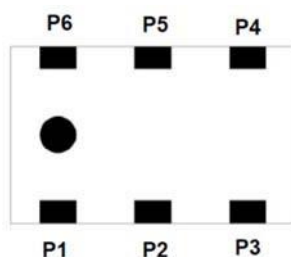
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

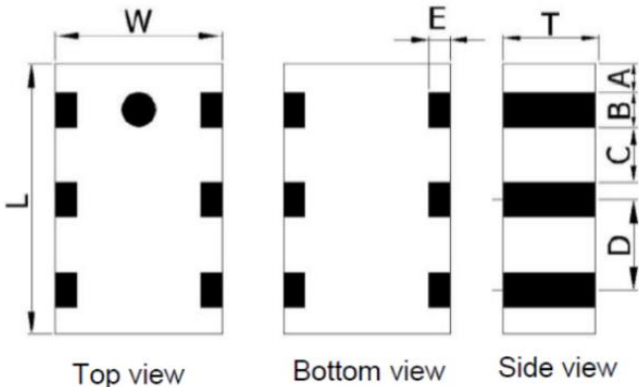
NO.	Parameter	SPC
1	Frequency range (f1)	2400~2500 MHz
	Frequency range (f2)	1570~1610 MHz
2	Insertion Loss (f1)	1.5 dB max. @ 2400~2500 MHz
	Insertion Loss (f2)	1.6 dB max. @ 1570~1610 MHz
3	Attenuation (f1)	20 dB min. @ 1570~1610 MHz
	Attenuation (f2)	20 dB min. @ 2400~2500 MHz
4	VSWR (In BW)	2.0 max.
5	Port Impedance	50Ω
6	Power	2.0 W max.
7	Operation Temperature Range	-40℃ ~ +85℃

Construction

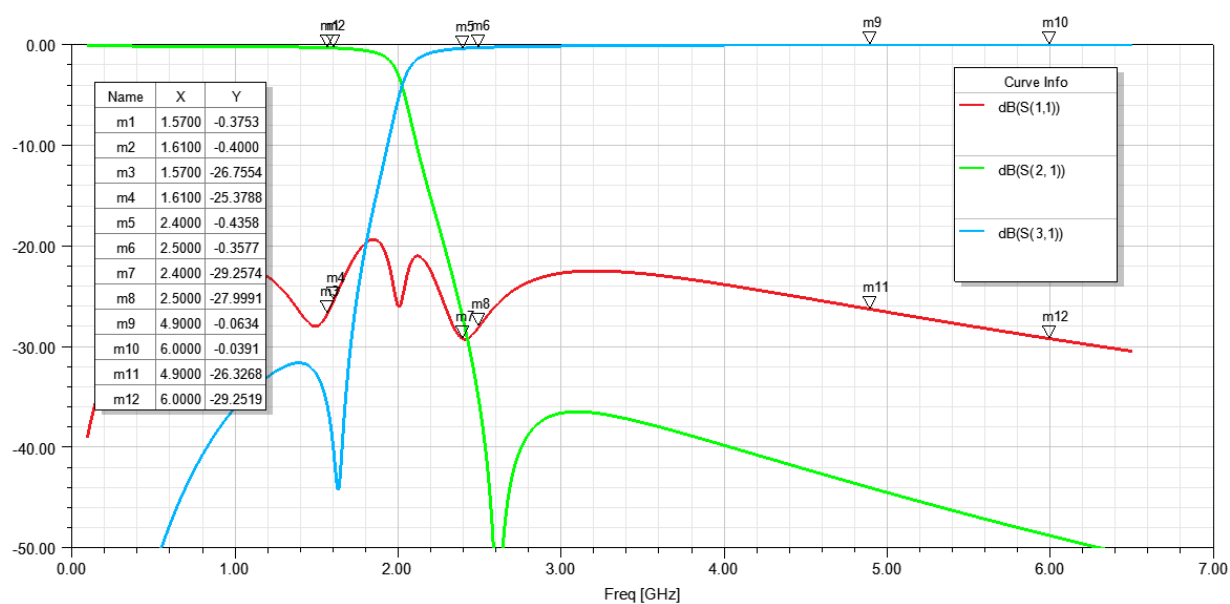


PIN	Connection	PIN	Connection
P1	GND	P4	Higher Port
P2	Antenna Input	P5	GND
P3	GND	P6	Low Port

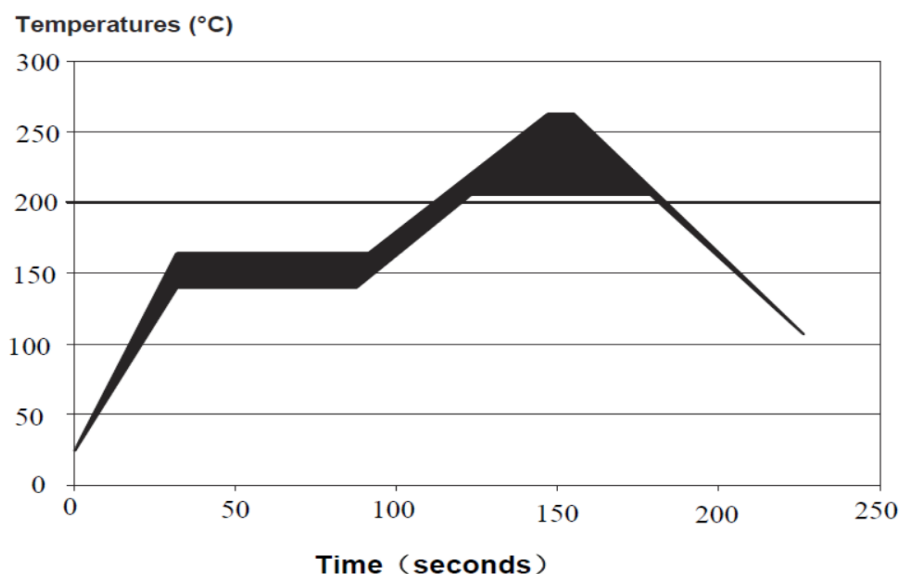
Dimensions

Figure	Symbol	Dimension (mm)
 Top view Bottom view Side view	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.2 ± 0.10
	B	0.2 ± 0.10
	C	0.3 ± 0.10
	D	0.5 ± 0.10
	E	0.15 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.